

The 23rd IEEE Hiroshima Section Student Symposium Papers Format

~(Subtitle if necessary)~

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1 Overview

This is the paper template for the 23rd IEEE Hiroshima Section Student Symposium, in which the format specification is explained in detail. When you prepare the manuscript of the paper, you should follow these instructions. No description is permitted in headers and footers.

2 Style

The document size should be A4. All margins (top, right, left and bottom) are 20mm. For the text code, use the SJIS.

2.1 Title and authors section

Use larger font for title. The font size must be around from 14pt to 16pt. For author's name, use 10pt. Write down each affiliation of all authors, even though they are different from each other.

2.2 Body

1. Text font size is 9pt or 10pt.
2. Body text should be arranged in 2 columns for 2 to 4 pages. (Do not insert page numbers)
3. Section titles should be 12pt size in boldface and subsection titles are 10pt.
4. Pay attention to consistency of technical terms throughout the paper.
5. Use brackets () for abbreviation. Footnoting is also available.
6. Numerical numbers should be expressed by Arabic numerals in principle.

2.3 Figures, tables and photos

1. Just as a suggestion, the appropriate number of figures, tables and photos is 1 or 2 per page.
2. Put a caption with a serial number for figures and tables.
3. Be careful with the thickness of lines, shadings, and the size of characters.
4. Do not forget to insert axis's names and units for both vertical and horizontal axes of graphs.

2.4 References

1. Citations should be indicated by a serial number with brackets in the text, like [1], of the relevant part.
2. Each reference should be independently numbered even if the authors are the same.
3. Be sure to show the source of literature citations. If necessary, get an approval from the author in advance.
4. The author's name should be shown with full name in Japanese or with initials in English.

3 Caution on patents

This symposium is not subject to Article 30, Paragraph 1 of the Patent Law (Exceptions to Loss of Novelty of Invention). Therefore, if you are planning to apply for a patent for your presentation at this symposium, please submit your patent application before the publication date of the proceedings (November 27, 2021).

4 Paper Submission for Review

When you submit a paper for review, access the paper submission system in the HISS website, input the necessary information (name, affiliation, address, etc.), and upload a PDF file (up to 5MB) of your paper before 17:00 on August 23, 2021 (Monday). If it is difficult for you to use the system, send your PDF file to the following address:
e-mail: hiss23tp@yamaguchi-u.ac.jp
with your name, address and affiliation.

5 Contact

If you have any inquiries or questions, please do not hesitate to contact us.

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References

- [1] T. Denki, H. Joho, "23rdHISS," IEEE, Vol. 1, No. 1, pp. 1-10, 2021.